

FAX: 610-646-0509

Registration

Yes, I plan to attend the Netzsch Thermal Analysis of Polymers for Industry and Development seminar Wednesday, June 24, 2009, at NPE – room N230A.

I will be attending the seminar along with the following person(s)

Unfortunately, I will not be able to attend, but please contact me; I am interested in the following applications:

My contact information (please type or print):

Name:

Company/Institution:

Address:

State/Province:

Zip Code/Post Code:

Phone:

Fax:

E-mail:



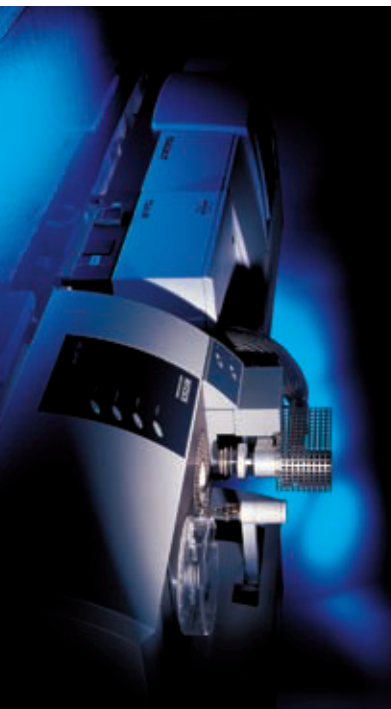
Leading Thermal Analysis

Thermal Analysis of Polymers
for Industry and Development
NPE 2009

Wednesday, June 24
McCormick Place, Chicago, IL

RSVP Required.

- Thermal Characterization
- Incoming Goods Inspection
- Quality Control & Assurance
- Failure Analysis
- Process Optimization
- Thermophysical Properties



How can I easily distinguish between different thermoplastics?
How can species evaporation be determined?

How does the atmosphere influence thermal stability?

How can the state of cross-linking be determined and the process optimized?

How can the plasticizer content of a rubber mixture be determined – and what plasticizer material is used?

How can curing be tracked during the process?

How can I distinguish between processing failure and material failure?

How do the visco-elastic properties of the damping element change under high-frequency stress?

How high is the degree of crystallinity of the semi-crystalline thermoplastic molding?

PRELIMINARY PROGRAM
Wednesday, June 24, 2009
McCormick Place – Room N230A
Chicago, IL

10:00 a.m. - 10:15 a.m. Introduction to NETZSCH

10:15 a.m. - 10:45 a.m. DSC & TGA Methods

10:45 a.m. - 11:30 a.m. Quality Control and Failure Analysis by DSC & TGA (Part 1)

11:30 a.m. - 12:00 p.m. Dielectric Analysis (DEA) for In-situ Cure Monitoring of Thermosetting Resins Composites, Molding Compounds, Paints and Coatings

Dielectric Analysis (DEA) for In-situ Cure Monitoring of Thermosetting Resins Composites, Molding Compounds, Paints and Coatings

12:00 p.m. - 12:30 p.m. Lunch

12:30 p.m. - 1:15 p.m.

Using Dynamic Mechanical Analysis (DMA) to Measure Visco-elastic Properties of Polymers and Composites

1:15 p.m. - 1:45 p.m.

Thermal Conductivity of Polymers, Polymer Melts, & Rubber by the Laser Flash Technique (LFA)

1:45 p.m. - 2:15 p.m.

Quality Control and Failure Analysis by DSC & TGA (Part 2)

2:15 p.m. - 2:30 p.m.

Wrap-Up & Final Discussion

Presented by:
NETZSCH Instruments, Inc.
www.e-thermal.com
www.netzsch-thermal-analysis.com

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Date	Location
24 June 2009	Chicago, IL

Please note that seating is limited. Reservations will be made on a first-come, first-served basis, so register soon to be sure you don't miss out on this opportunity.

We are looking forward to welcoming you to our seminar.

FREE SEMINAR - RSVP REQUIRED

Seminar Goals

Modern thermo-analytical methods are an excellent tool for answering such questions in product development, quality control & assurance, failure analysis and research of new products. These methods are even more powerful when coupled to other techniques.

The goal of the seminar is to demonstrate the capabilities of these methods with real-case applications from the fields of thermoplastics, thermosets, rubbers, etc.

